



**/ Absolute Maximum Ratings(Ta=25 )**

Parameter	Symbol	Rating	Unit
Peak pulse power (tp = 8/20μs)	PK	69	W
Peak pulse current (tp = 8/20μs)	IPP	5.5	A
ESD according to IEC61000-4-2 air discharge	VESD	±30	KV
ESD according to IEC61000-4-2 contact discharge		±30	
Junction temperature	TJ	150	
Storage temperature	TSTG	-55~+150	

**/ Electrical Characteristics(Ta=25 )**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse maximum working voltage	VRWM				3.3	V
Reverse leakage current	IR	VRWM =3.3V			0.1	uA
Reverse breakdown voltage <sup>1)</sup>	VBR	IT = 1mA	5.0		6.8	V
Clamping voltage <sup>2)</sup>	VC	IPP = 1A tp = 8/20μs			9.8	V
		IPP = 5.5A tp = 8/20μs			12.5	V
Junction capacitance	CJ	VR = 0V f = 1MHz			15	pF

Notes:

- 1) VBR is measured with a pulse test current IT at an ambient temperature of 25 .
- 2) Non-repetitive current pulse, according to IEC61000-4-5.

/ Electrical Characteristic Curve



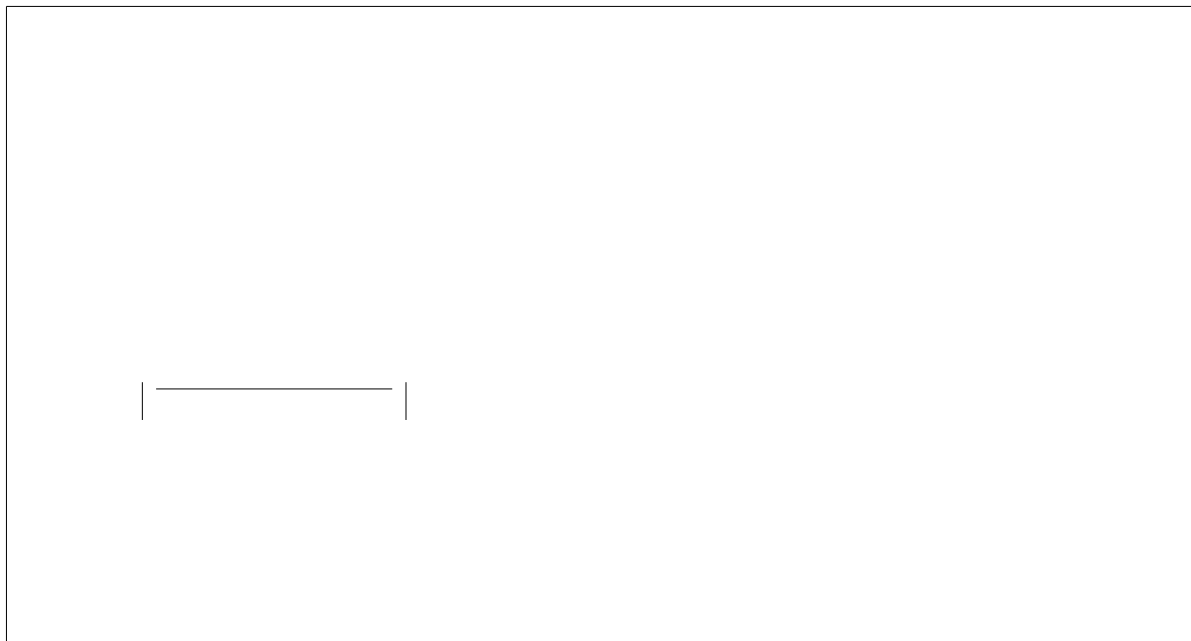
# BRES3V3L1B2Z

Rev.C Oct.-2022

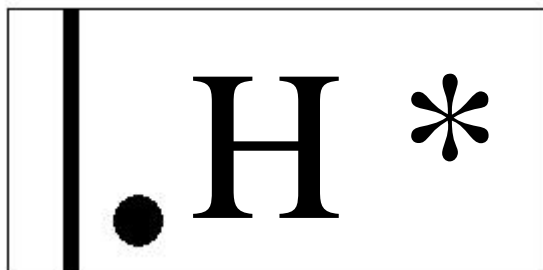
## / Package Dimensions

DFN0603

Unit:mm



/ Marking Instructions



Note

H

Product Type

\*

Lot No. Code,code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)


Note:

- |   |     |     |    |          |   |
|---|-----|-----|----|----------|---|
| 1 | 150 | 180 | 60 | 90sec;   | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245 | 5   | 5  | 0.5sec;  | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 |     |     | 2  | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

605 5